

PATENT

TESSERA 3.3-018 CONT CONT II CONT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of
Khandros et al.

Serial No.: Unassigned

Filed: On Even Date Herewith

For: Face-Up Semiconductor
Chip Assembly

Group Art Unit:

Examiner:

Date: July 6, 1998

X

Assistant Commissioner For Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir or Madame:

Preliminary to the initiation of the prosecution of the above-identified pending U.S. patent application, the following amendments and remarks are respectfully submitted.

In the Title:

Please amend the title of the application to: --Face-up Semiconductor Chip Assembly --.

In the Specification:

Please insert before the first line, after the title, the following:

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation of United States Patent Application No. 08/861,280, filed on May 21, 1997 which is in turn a continuation of United States Patent Application No. 08/319,966, filed on October 7, 1994, now United States Patent No. 5,685,885. United States Patent Application No. 08/319,966 is a

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